ADE 7200 WaferCheck System Configuration and Specification

Non-contact capacitive probe measurement for 400 – 1000 µm wafer thickness range

Capable of measuring： Lapped, Etched, Polished and Patterned Wafers

Measures bow and warp, Site and Global flatness, thickness and resistivity

System consist of:

- 2 Cassette input stations
- 6 Cassette output stations
- Pre-Aligner station
- Hi Res Station
- Lo Res Station
- E Gage thickness
- Power Conditioner
- Unix Controller Computer

Measurement Specifications:

	Accuracy	Repeatability (1σ)	Absolute Range
Thickness	± 0.50 µm	0.15 µm	Nominal ± 125µm
Shape (Bow/Warp)	± (4.0 + 5% of reading) µm	(1.3 + 1% of reading) µm	± 150 µm
Global Flatness	± 0.15 µm	0.05 µm	
Site Flatness	± 0.15 µm	0.05 um	
Resistivity: Low		0.9%	0.001 – 0.999 ohm-cm
High		0.25%	0.2 – 199.9 ohm-cm
Dual		1%	0.001 – 99.9 ohm-cm

Thickness range:	400 µm to 1,000 µm
Notches, Flats:	Up to four per SEMI and JEIDA standards
Edge exclusion:	Up to 3 mm from edge

Throughput:	100 - 1000 wafers/hour (depends on wafers size, measurement pattern and mode)
Dimensions & Weight:	TBD
Power requirement:	Configurable from 200 to 240 VAC @ 50/60 Hz (4.8 kVA peak)